WHAT IS CLAIMED IS:

1. A chuck table for holding a wafer, comprising:

a holding plate having a holding surface for holding the wafer under suction; and

a frame body that supports the holding plate thereon and transmits a negative pressure or a positive pressure to the holding surface,

wherein the holding plate includes a plurality of cleaved portions by which the holding plate is cleaved into a plurality of blocks along a plurality of modified layers by applying a laser beam of a wavelength, which has transmissivity through the holding plate, with a focal point thereof positioned inside the holding plate, and the negative pressure or the positive pressure is transmitted from the cleaved portions to the holding surface.

2. A grinding machine comprising:

a chuck table according to claim 1, that holds a wafer;

a grinding unit that includes a grinding wheel for rotation with a plurality of grinding stones disposed in an annular pattern thereon to grind the wafer held on the chuck table; and

a grinding water supply unit that supplies grinding

water to the grinding stones and the wafer.

3. A manufacturing method of a chuck table according to claim 1, including a holding surface that holds a wafer thereon, comprising:

a base material providing step of providing a base material for a holding plate;

a modified layer forming step of forming a plurality of modified layers by applying a laser beam of a wavelength, which has transmissivity through the base material, with a focal point thereof positioned inside the base material,

a cleaving step of forming a plurality of cleaved portions by cleaving the base material into a plurality of blocks along the modified layers, and

an integration step of integrating the holding plate, in which the cleaved portions have been formed, with a frame body that supports the holding plate thereon.